TIL187-1 THRU TIL187-4 TIL188-1 THRU TIL188-4 AC-INPUT OPTOCOUPLERS/OPTOISOLATORS

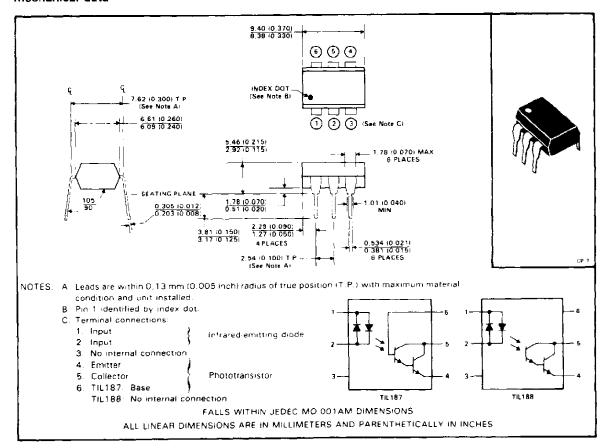
SOOS012A D2980. JANUARY 1987-REVISED JULY 1989

- AC Signal Input
- Gallium Arsenide Dual-Diode Infrared Source Optically Coupled to a Silicon N-P-N Darlington Phototransistor
- Plastic Dual-In-Line Package
- High-Voltage Electrical Isolation, 3.535 kV Peak (2.5 kV rms)
- High Current Transfer Ratio, 500% Minimum at IF = 10 mA, Up to 1500% Minimum at IF = 2 mA with Four Categories
- High V(BR)CEO, 55 V Min
- UL Recognized File #E65085
- No Base Lead Connection on TIL188 for High-FMI Environment

description

The TIL187 and TIL188 Optocouplers are designed for use in AC applications that require very high current transfer ratio and high voltage isolation between input and output. These optocouplers consist of two GaAs light-emitting diodes connected in a reverse-parallel configuration and a silicon n-p-n Darlington phototransistor. The TIL187 has the base connected for applications where a base signal or base resistor is required. The TIL188 is designed with no base connected for applications where high base-noise immunity is desired. Users can select from four different current gains (TIL187-1 through TIL188-4).

mechanical data



PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the torons of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



TIL187-1 THRU TIL187-4 TIL188-1 THRU TIL188-4 AC-INPUT OPTOCOUPLERS/OPTOISOLATORS

absolute maximum ratings at 25 °C free-air temperature (unless otherwise noted)

Input-to-output voltage
Collector-emitter voltage (see Note 1)
Emitter-collector voltage
Emitter-base voltage (TIL187)
Input diode continuous forward current at (or below) 25 °C free-air temperature (see Note 2)
Continuous power dissipation at (or below) 25 °C free-air temperature:
Infrared-emitting diode (see Note 3)
Phototransistor (see Note 3)
Total, infrared-emitting diode plus phototransistor (see Note 4)
Storage temperature range55°C to 150°C
Lead temperature 1,6 mm (1/16-inch) from case for 10 seconds

- NOTES: 1 This value applies when the base-emitter diode is open circuited.

 - Derate linearly to 100 °C free-air temperature at the rate of 1.33 mA/°C.
 Derate linearly to 100 °C free-air temperature at the rate of 2 mW/°C
 - 4. Denote linearly to 100 $^{\circ}\text{C}$ free-air temperature at the rate of 3.33 mW/ $^{\circ}\text{C}$

electrical characteristics at 25 °C free-air temperature (unless otherwise noted)

	PARAMETER			TIL187			TIL188			
			TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vissiana	Collector-base breakdown voltage		$I_C = 10 \mu A$, $I_E = 0$,	100						
V(BR)CBO			le = 0						_	*
V(BR)CEO breakdown voltage		I _C = 1 mA, I _B = 0,	55			55			V	
		lF = 0								
V(BR)EBO Emitter-base		l _E = 10 μA, l _C = 0,	14						v	
*18H)EBO	breakdown voltage		IF = 0	, , ,						<u> </u>
Emitter-collector		· ·	le = 10 μA, le = 0				7		1	V
- (BNIECO	breakdown voltage									
On-s		TIL187-1, TIL188-1	_	5			5			mA
	Photo-	TIL187-2, TIL188-2	3 IB = 0	10			10			
	state transistor	TIL187-3, TIL188 3		20	-		20			
IC(on) colle	ctor operation	TIL187-4, TIL188-4		30			30			
Curr	ł		V _{CE} = 1 V, I _F = 10 mA, I _B = 0	50			50			
	Photodio	de operation	V _{CB} = 1 V, I _F = 10 mA,	12						μA
	Officers		V _{CF} = 10 V, I _F = 0.				1			
IC(off)	Off-state collector current					100			100	пA
	Transistor static		IB = 0	 -						
hFE	forward current		V _{CE} = 1 V, I _C = 10 mA, I _F = 0		25000	5000				
	transfer ratio				20000					
∨ _F †	Input diode static forward voltage		lp = 10 mA	1	1.2	1.5	1	1.2		
									1.5	V
	Collector-emit	_	IC = 50 mA, IF = 10 mA,							
VCE(sat)	saturation voltage		i _B = 0		0.87	1		Q.87	1	V
rio	Input-to-output		V _{In-aut} = ±500 V, See Note 5	1011	-		1011			
	internal resistance									Ω
Cip	Input-to-output		$V_{in-out} = 0$, $f = 1$ mHz,		1	1.3		1	1.3	ρF
	capacitance		See Note 5		, I	1.3			1.3	μ-
IC(on)1	C(on)1 On-state collector current		V _{CE} = 1 V, I _F = 2 mA	1		3	1		3	
IC(on)2 symmetry ratio (see Note 6)		io (see Note 6)					<u> </u>			

 $[\]ensuremath{^{\dagger}}\xspace$ These parameters apply for either direction of the input current.

NOTES: 5. These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

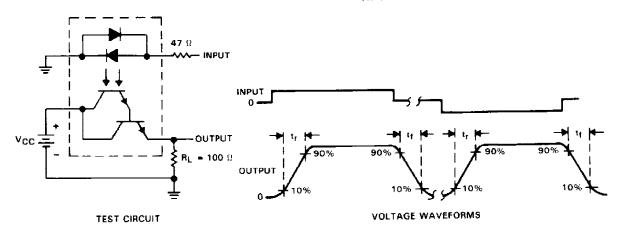
6. The higher of the two IC(on) values generated by the two diodes is taken as IC(on)1.

switching characteristics at 25 °C free-air temperature

PARAMETER	TEST CONDITIONS			TIL187			TIL188		
PARAMETER				TYP	MAX	MIN	TYP	MAX	UNIT
t _f Rise time	V _{CC} = 10 V.	I _{Cloni} = 10 mA,		100			100		μS
t _f Fall time	R_L - 100 Ω ,	see Figure 1		100			100		μS

PARAMETER MEASUREMENT INFORMATION

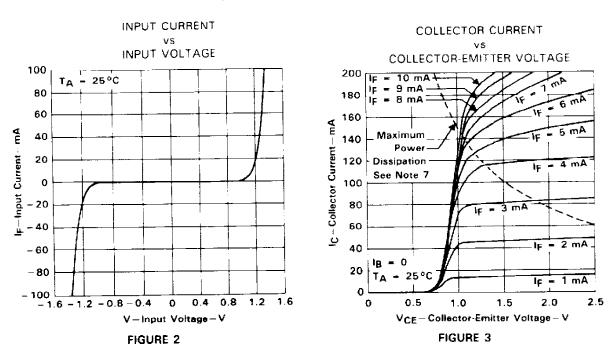
Adjust amplitude of input pulse is for IC(on) = 10 mA



NOTES: A The input waveform is supplied by a generator with the following characteristics: $|Z_0| = 50 \,\Omega$, $t_r = \pm 15$ ns, duty cycle = 1%. B. The output waveform is monitored on an oscilloscope with the following characteristics: $|t_r| \le 12$ ns, $|R_1| \ge 1$ M Ω , $|C_n| \le 20$ pF.

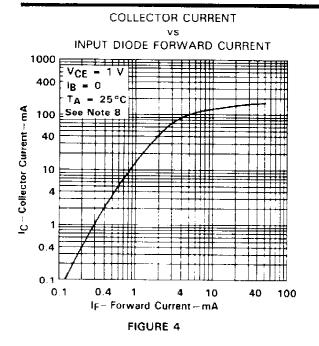
FIGURE 1. SWITCHING TIMES

TYPICAL CHARACTERISTICS



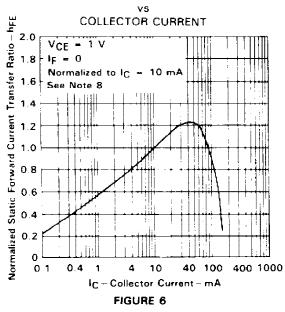
Note 7: Pulse operation is required for operation beyond limits shown by the dashed line.

NORMALIZED ON STATE COLLECTOR CURRENT



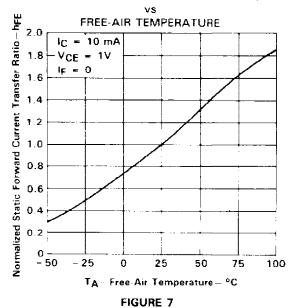
VS FREE-AIR TEMPERATURE VCE = 1 V IF = 10 mA IB = 0 Normalized Collector Current-IC(on) 1.0 IF - 2 mA 0.8 0.6 0.4 0.2 0 -50 - 25 0 25 50 75 100 TA-Free-Air Temperature- °C

TIL187
NORMALIZED TRANSISTOR STATIC
FORWARD CURRENT TRANSFER RATIO



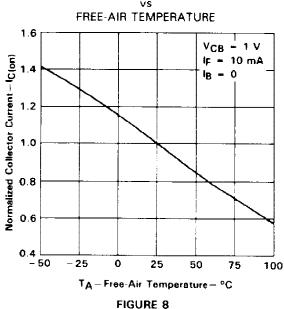
TIL187
NORMALIZED TRANSISTOR STATIC
FORWARD CURRENT TRANSFER RATIO

FIGURE 5



NOTE 8: These parameters were measured using pulse techniques $t_{W} = 1$ ms, duty cycle $\leq 2\%$.

TIL187 NORMALIZED ON-STATE COLLECTOR CURRENT (PHOTODIODE OPERATION)



NORMALIZED COLLECTOR-EMITTER BREAKDOWN VOLTAGE Normalized Collector-Emitter Breakdown Voltage V(BRICEO vs FREE-AIR TEMPERATURE 1.3 Ic = 1 mA $l_B = 0$ 1.2 IF = 01.1 1.0 0.9 0.8

TA-Free-Air Temperature- °C

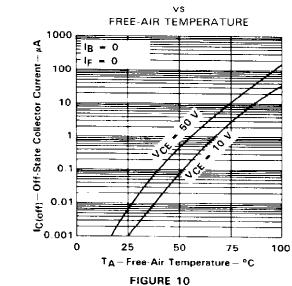
FIGURE 9

- 25

OFF-STATE COLLECTOR CURRENT

0.7

- 50



100

50

75

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